

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| - | 50 | 257/778 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/21 18:07 |
| - | 21 | 257/779 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 07:24 |
| - | 18 | 257/780 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/26 17:25 |
| - | 29 | 257/784 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/26 17:28 |
| - | 32 | 257/787 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/26 17:53 |
| - | 241 | 257/778 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 08:14 |
| - | 77 | 257/779 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 08:49 |
| - | 140 | 257/780 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:54 |
| - | 62 | 257/781 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:16 |
| - | 102 | 257/786 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:22 |
| - | 131 | 257/787 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:28 |
| - | 235 | 257/737 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:39 |
| - | 187 | 257/738 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:45 |
| - | 36 | 257/697 and chip and (ball or bump) and (electrode adj pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:45 |

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| - | 1441 | 257/780 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/27 09:55 |
| - | 1998 | 257/698 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/21 15:53 |
| - | 24 | "5741729" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/26 12:20 |
| - | 22 | "5498901" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/21 16:29 |
| - | 24 | "5825628" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/21 16:44 |
| - | 23 | "5903050" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/21 16:47 |
| - | 31 | "5677575" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/21 16:47 |
| - | 232 | 257/778 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/22 09:02 |
| - | 86 | 257/779 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/22 09:12 |
| - | 111 | 257/780 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/22 09:38 |
| - | 40 | 257/781 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/22 09:40 |
| - | 96 | 257/784 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/22 11:10 |
| - | 121 | 257/787 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/22 11:46 |
| - | 192 | 257/738 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/07/26 12:37 |

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| - | 36 | 257/680 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 13:06 |
| - | 106 | 257/690 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 13:49 |
| - | 116 | 257/692 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 13:54 |
| - | 90 | 257/693 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 14:03 |
| - | 150 | 257/698 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 14:12 |
| - | 101 | 438/108 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 14:19 |
| - | 10 | 438/116 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 14:21 |
| - | 64 | 438/612 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 14:24 |
| - | 47 | 438/614 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/22 14:26 |
| - | 36 | 438/617 and chip and substrate and ring and ball and wire | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/26 12:53 |
| - | 26 | 257/\$.ccls. and (ceramic adj substrate adj insulating) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/07/27 10:11 |